Docket No. AM1562D1

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Divisional Application of

JOAN WANG

Filed: Herewith

For: METHOD OF ETCHING HIGH ASPECT RATIO

OPENINGS IN SILICON

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.56

To: Assistant Commissioner for Patents

Washington, DC 20231

Sir:

The following references were referred to during preparation of the above-identified patent application.

US Patent 4,617,086 to Chuang et al.

US Patent 4,726,879 to Bondur et al.

US Patent 5,013,398 to Long et al.

US Patent 5,110,411 to Long.

US Patent 5,160,408 to Long.

US Patent 5,200,028 to Tatsumi.

US Patent 5,211,790 to Tatsumi.

US Patent 5,449,433 to Donohoe.

US Patent 5,453,156 to Cher et al.

US Patent 5,458,734 to Tsukamoto.



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US Patent 5,498,312 to Laermer et al.

US Patent 5,522,966 to Komura et al.

US Patent 5,536,364 to Yoshida et al.

US Patent 5,545,290 to Douglas.

The following references have been cited in applicant's PCT application.

US Patent 4,855,017 to Douglas

US Patent 5,010,378 to Douglas

US Patent 5,423,941 to Komura et al

EP Application 489,407 A2 to Collins et al. This application corresponds to US Patent 5,556,501.

EP Application 272,143 A2 to Wong et al. This application corresponds to US Patent 5,874,362.

The following references were cited in applicant's CIP application.

US Patent 5,354,417 to Cheung et al.

US Patent 4,729,815 to Leung

US Patent 5,262,002 to Grewal et al

US Patent 5,180,464 to Tatsumi et al.

US Patent 5,259,923 to Hori et al.

Japan Kokai 6 [1994] 163481

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## PCT Examination Report

A copy of the references are attached hereto. Applicants request these references be made part of the application file.

Respectfully submitted,

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Please continue to send all correspondence to Patent Counsel Applied Materials, Inc PO Box 450A Santa Clara, CA 95052